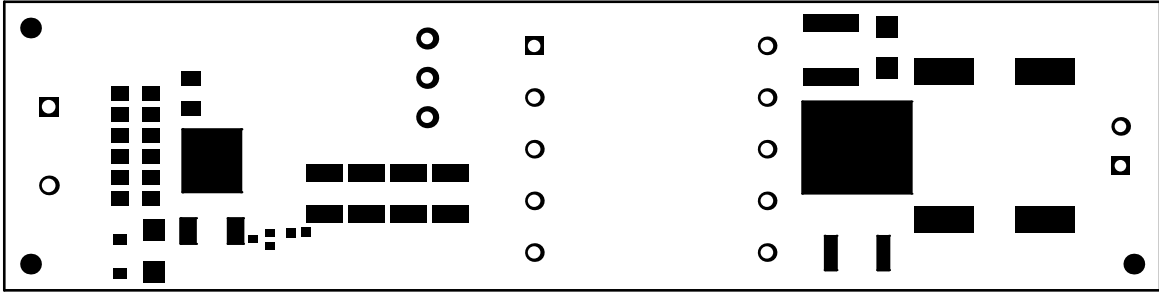
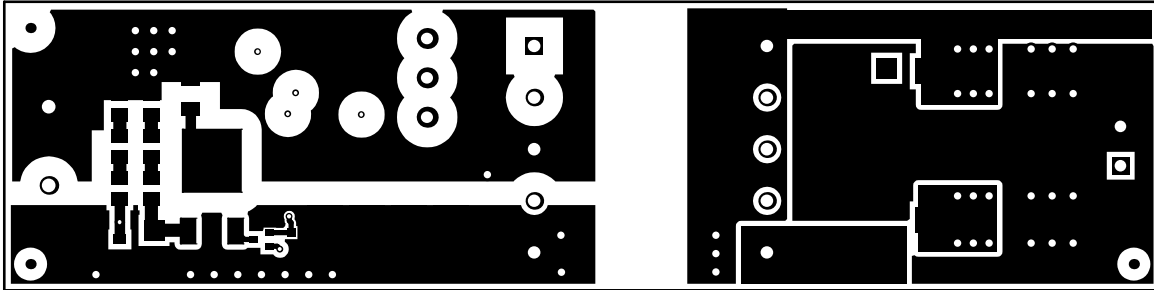


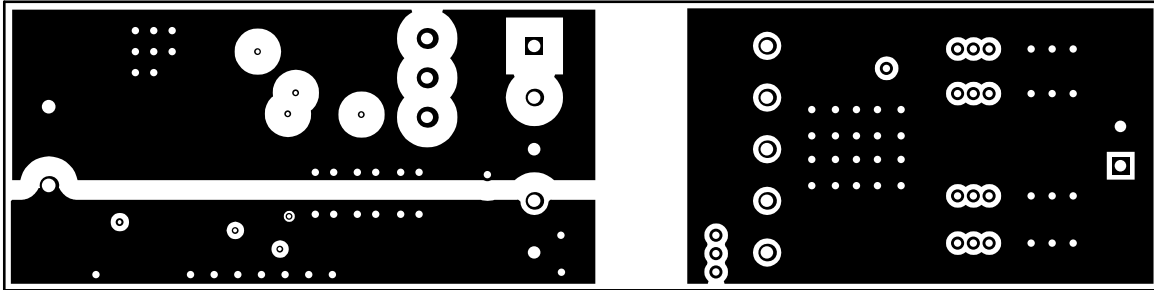
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP9334		
PLOT NAME = Top Overlay	GENERATED : 5/8/2016	8:30:53 PM	TEXAS INSTRUMENTS



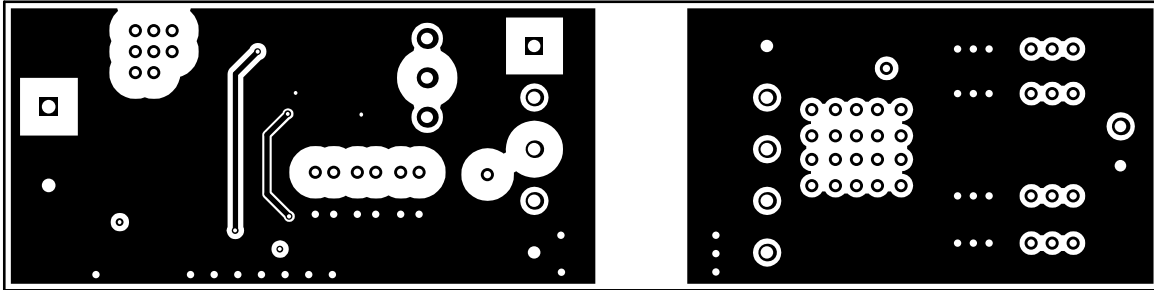
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP9334		
PLOT NAME = Top Solder Mask	GENERATED : 5/8/2016	8:30:54 PM	TEXAS INSTRUMENTS



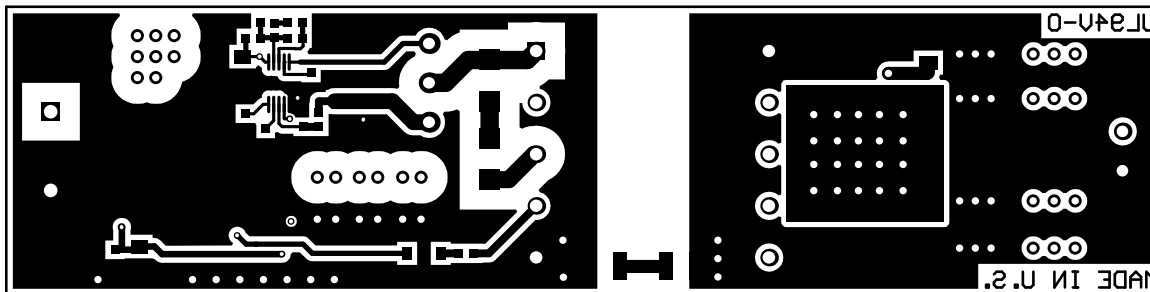
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP9334		
PLOT NAME = Top Layer	GENERATED : 5/8/2016 8:30:54 PM	TEXAS INSTRUMENTS	



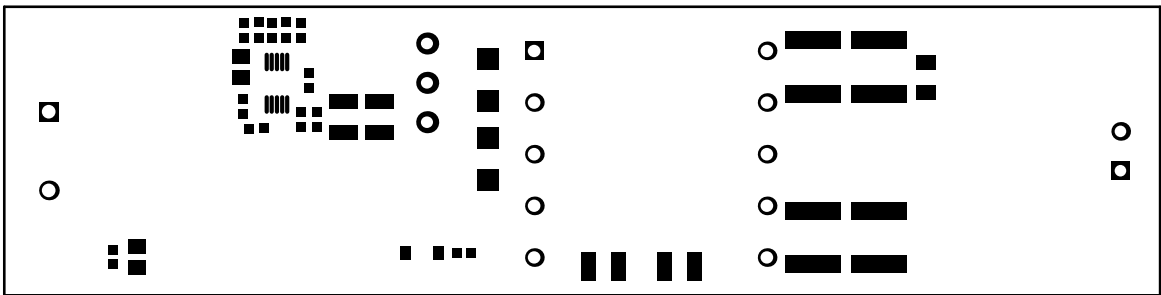
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: C	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP9334		
PLOT NAME = Signal Layer 1	GENERATED : 5/8/2016 8:30:55 PM	TEXAS INSTRUMENTS	



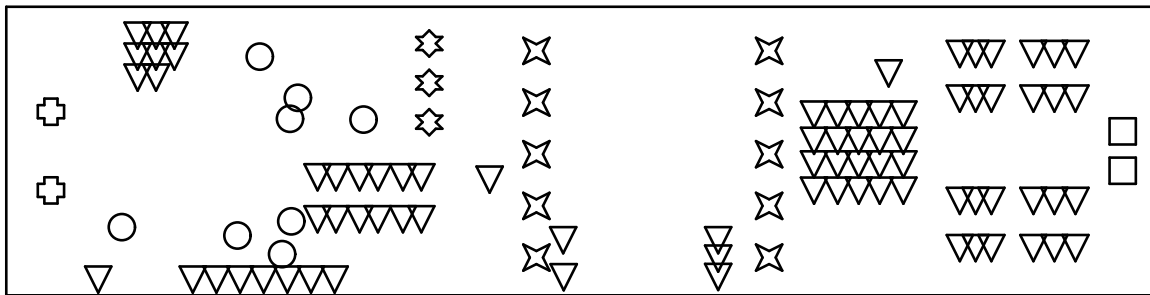
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: C	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP9334		
PLOT NAME = Signal Layer 2	GENERATED : 5/8/2016 8:30:55 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP9334		
PLOT NAME = Bottom Layer	GENERATED : 5/8/2016	8:30:56 PM	TEXAS INSTRUMENTS

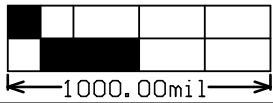


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP9334		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/8/2016 8:30:56 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	8	15.00mil (0.381mm)	PTH	Round
▽	79	28.00mil (0.711mm)	PTH	Round
□	2	43.31mil (1.100mm)	PTH	Round
✱	3	45.00mil (1.143mm)	PTH	Round
✕	10	47.24mil (1.200mm)	PTH	Round
⊗	2	51.18mil (1.300mm)	PTH	Round
	104 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP9334		
PLOT NAME = Drill Drawing	GENERATED : 5/8/2016	8:30:58 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9334	REV: C	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP9334		
PLOT NAME = Board Dimensions	GENERATED : 5/8/2016 8:30:58 PM		TEXAS INSTRUMENTS

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